
Integrirana vezja - Meritve elektromagnetnega sevanja od 150 kHz do 1 GHz - 8.
del: Merjenje sevanega oddajanja - Metoda z IC na tračnem valovodu

Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 8: Measurement of radiated emissions - IC stripline method

Integrierte Schaltungen - Messung von elektromagnetischen Aussendungen - Teil 8: Messung der abgestrahlten Aussendungen - IC-Streifenleiterverfahren

Circuits intégrés - Mesure des émissions électromagnétiques -- Partie 8: Mesure des émissions rayonnées - Méthode de la ligne TEM à plaques (stripline) pour CI

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Ta slovenski standard je istoveten z: EN 61967-8:2011

ICS:

31.200	Integrirana vezja, mikroelektronika	Integrated circuits. Microelectronics
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SIST EN 61967-8:2012

en,fr,de

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 61967-8

October 2011

ICS 31.200

English version

**Integrated circuits -
Measurement of electromagnetic emissions -
Part 8: Measurement of radiated emissions -
IC stripline method
(IEC 61967-8:2011)**

Circuits intégrés -
Mesure des émissions
électromagnétiques -
Partie 8: Mesure des émissions
rayonnées -
Méthode de la ligne TEM à plaques
(stripline) pour CI
(CEI 61967-8:2011)

Integrierte Schaltungen -
Messung von elektromagnetischen
Aussendungen -
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Aussendungen -
IC-Streifenleiterverfahren
(IEC 61967-8:2011)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 47A/868/FDIS, future edition 1 of IEC 61967-8, prepared by SC 47A, "Integrated circuits", of IEC TC 47, "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61967-8:2011.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2012-06-15
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2014-09-15

This standard is to be used in conjunction with EN 61967-1.

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050-131	-	International Electrotechnical Vocabulary (IEV) - Part 131: Circuit theory	-	-
IEC 60050-161	-	International Electrotechnical Vocabulary (IEV) - Chapter 161: Electromagnetic compatibility	-	-
IEC 61000-4-20	-	Electromagnetic compatibility (EMC) - Part 4-20: Testing and measurement techniques - Emission and immunity testing in transverse electromagnetic (TEM) waveguides	EN 61000-4-20	-
IEC 61967-1	-	Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 1: General conditions and definitions	EN 61967-1	-
IEC 61967-2	-	Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 2: Measurement of radiated emissions - TEM cell and wideband TEM cell method	EN 61967-2	-

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IEC 61967-8

Edition 1.0 2011-08

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Integrated circuits – Measurement of electromagnetic emissions –
Part 8: Measurement of radiated emissions – IC stripline method**

**Circuits intégrés – Mesure des émissions électromagnétiques –
Partie 8: Mesure des émissions rayonnées – Méthode de la ligne TEM à plaques
(stripline) pour CI**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

PRICE CODE
CODE PRIX



ICS 31.200

ISBN 978-2-88912-619-4

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**INTEGRATED CIRCUITS –
MEASUREMENT OF ELECTROMAGNETIC EMISSIONS –**
**Part 8: Measurement of radiated emissions –
IC stripline method**

FOREWORD

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International Standard IEC 61967-8 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47A/868/FDIS	47A/870/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

This part of IEC 61967 is to be read in conjunction with IEC 61967-1.

A list of all parts of IEC 6xxxx series, under the general title *Integrated circuits – Measurement of electromagnetic emissions* can be found on the IEC website.

NOTE Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTEGRATED CIRCUITS – MEASUREMENT OF ELECTROMAGNETIC EMISSIONS –

Part 8: Measurement of radiated emissions – IC stripline method

1 Scope

The measurement procedure of this part of IEC 61967 defines a method for measuring the electromagnetic radiated emission from an integrated circuit (IC) using an IC stripline in the frequency range of 150 kHz up to 3 GHz. The IC being evaluated is mounted on an EMC test board (PCB) between the active conductor and the ground plane of the IC stripline arrangement.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-131: *International Electrotechnical Vocabulary (IEV) – Part 131: Circuit theory*

IEC 60050-161: *International Electrotechnical Vocabulary (IEV) – Chapter 161: Electromagnetic compatibility*

IEC 61967-1: *Integrated circuits – Measurement of electromagnetic emissions, 150 kHz to 1 GHz – Part 1: General conditions and definitions*

IEC 61967-2: *Integrated circuits – Measurement of electromagnetic emissions, 150 kHz to 1 GHz – Part 2: Measurement of radiated emissions – TEM cell and wideband TEM cell method*

IEC 61000-4-20: *Electromagnetic compatibility (EMC) – Part 4-20: Testing and measurement techniques – Emission and immunity testing in transverse electromagnetic (TEM) waveguides*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 61967-1, IEC 60050-131 and IEC 60050-161 as well as the following apply.

3.1

transverse electromagnetic (TEM) mode

waveguide mode in which the components of the electric and magnetic fields in the propagation direction are much less than the primary field components across any transverse cross-section

3.2

TEM waveguide

open or closed transmission line system, in which a wave is propagating in the transverse electromagnetic mode to produce a specified field for testing purposes